



3DP&I Joint Bonded Wafer Stacks and Inspection & Metrology TF

NA Standards Spring Meetings 2020

Thursday, April 2

11:00–12:00 (Pacific) via Web Conference

AGENDA

	Time
1 Welcome/Call to Order	11:00
1.1 Introductions and Announcements	
1.2 Required Elements (Membership Requirements, Antitrust and Intellectual Property Reminders, and Effective Meeting Guidelines)	
1.3 Agenda Review	
2 Review of Previous Meeting Minutes	11:05
3 Ballot Review/Discussion	11:10
3.1 Document 6631 — Line Item Revision to SEMI 3D12-0315, Guide for Measuring Flatness and Shape of Low Stiffness Wafers	
4 Old Business	11:25
4.1 Activities between meetings	
• Document 6641: Revision to SEMI 3D8-0514, Guide for Describing Silicon Wafers for Use as 300 mm Carrier Wafers in a 3DS-IC Temporary Bond-Debond (TBDB) Process	
4.2 Standards coming up for Five-Year Review	
• SEMI 3D13-0715, Guide for Measuring Voids in Bonded Wafer Stacks	
• SEMI 3D4-0915, Guide for Metrology for Measuring Thickness, Total Thickness Variation (TTV), Bow, Warp/Sori, and Flatness of Bonded Wafer Stacks	
5 New Business	11:45
6 Action Item Review	11:50
7 Next Meeting and Adjournment	11:55
7.1 The next meeting is scheduled for Thursday, July 23, 2020 in conjunction with SEMICON West 2020. Time?	



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